

Title (en)
TOLERANCE COMPENSATION ELEMENT FOR CIRCUIT CONFIGURATIONS

Title (de)
TOLERANZAUSGLEICHSELEMENT FÜR SCHALTBILDER

Title (fr)
ÉLÉMENT DE COMPENSATION DE TOLÉRANCES POUR SCHÉMAS DE CONNEXIONS

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EP 3622786 A1 20200318 (DE)

Application
EP 18734092 A 20180607

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Abstract (en)
[origin: WO2019007624A1] The invention relates to a tolerance compensation element for circuit configurations having a DCB (direct copper bonded) substrate (1) and a PCB (printed circuit board) (2) and to a circuit configuration having said tolerance compensation element. The invention is characterized in that a tolerance compensation element is positioned in a targeted manner between the DCB substrate (1) and PCB (2) in a gap A (3) for the contact-connection of components (5) on the DCB substrate (1) by means of additive manufacturing and is formed so as to close the gap.

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Citation (search report)
See references of WO 2019007624A1

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